

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0004] with the following new paragraph:

[0004] Further representative embodiments of the present invention are directed to a system for dissipating heat generated in an electronic assembly comprising means for moving heat from the electronic assembly to a plurality of conductive columns extending perpendicularly from a base plate in contact with the electronic assembly, means for moving heat from the plurality of conductive columns to one or more thermal plates connected at predetermined distances along the plurality of conductive columns, wherein each one of the one or more thermal plates has an orifice there through, and means for transferring heat from the plurality of conductive columns and the one or more thermal plates to air flowing in a direction perpendicular to the one or more thermal plates ~~base-plate~~, and a direction parallel to the one or more thermal plates.